Product / Package Information

Package	LFCSP
Body Size (mm)	2 X 2
Lead Count	6
Terminal Finish	NiPdAu
MS Number	MS012349A

Environmental Compliance Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.07E-03	93.70	937000	27.15	271469
Thermosets	Epoxy Resin	Proprietary	6.63E-05	3.00	30000	0.87	8692
Thermosets	Phenol Resin	Proprietary	6.63E-05	3.00	30000	0.87	8692
Other inorganic materials	Carbon Black	1333-86-4	6.63E-06	0.30	3000	0.09	869
Subtotal			2.21 E-03	100.00	1000000	28.97	289721

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.65 E-03	97.50	975000	60.98	609829
Copper & its alloys	Iron	7439-89-6	1.12 E-04	2.35	23500	1.47	14698
Copper & its alloys	Zinc	7440-66-6	5.73 E-06	0.12	1200	0.08	751
Copper & its alloys	Phosphorus	7723-14-0	1.43 E-06	0.03	300	0.02	188
Subtotal			4.77 E-03	100.00	1000000	62.55	625466

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	2.47 E-04	87.5	875000	3.23	32348
Precious metals	Palladium	7440-05-3	3.23 E-05	11.5	114600	0.42	4237
Precious metals	Gold	7440-57-5	2.93 E-06	1.0	10400	0.04	384
Subtotal			2.82 E-04	100.0	1000000	3.70	36970

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.28 E-05	99.0	990000	0.30	2988
Precious metals	Palladium	7440-05-3	2.30 E-07	1.0	10000	0.003	30
Subtotal			2.30 E-05	100.0	1000000	0.30	3018

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	1.21 E-04	100.0	1000000	1.58	15844

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.41 E-05	80.50	805000	0.97	9718
Other organic materials	Carbocyclic Acrylates	Proprietary	9.21 E-06	10.00	100000	0.12	1207
Other organic materials	Bismaleimide resin	Proprietary	2.76 E-06	3.00	30000	0.04	362
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	2.76 E-06	3.00	30000	0.04	362
Others	Additive	Proprietary	2.76 E-06	3.00	30000	0.04	362
Other organic materials	Dicumyl peroxide	80-43-3	4.60 E-07	0.50	5000	0.01	60
Subtotal			9.21 E-05	100.00	1000000	1.21	12072

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	7.79 E-05	60.40	604000	1.02	10213
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	3.61 E-05	28.00	280000	0.47	4735
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.29 E-05	10.00	100000	0.17	1691
Other organic materials	Ethylbenzene	100-41-4	1.29 E-06	1.00	10000	0.02	169
Other organic materials	Xylene	1330-20-7	7.74 E-07	0.60	6000	0.01	101
Subtotal			1.29 E-04	100.00	1000000	1.69	16909

	Weight (g)	Percentage (%)	PPM
Package Totals	**7.63 E-03**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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